AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-9 (canceled)

10.(original) A mounting method of a semiconductor device for mounting a semiconductor chip provided with a plurality of solder balls on a wiring substrate provided with a plurality of connection pads, comprising:

providing an insulating sheet having holes corresponding to said connection pads and having a plurality of leads, one end of each of said leads being fixed on a first surface of said insulating sheet and the other end of each of said leads protruding from a second surface of said insulating sheet through one of said holes;

electrically connecting said other end of each of said leads of said insulating sheet to a corresponding one of said connection pads; and

electrically connecting each of said solder balls to said fixed one end of a corresponding one of said leads.

11.(original) The mounting method of a semiconductor device as claimed in claim 10, further comprising:

filling resin into the gap between said insulating sheet and said wiring substrate after said connecting said other end of each of said leads to a corresponding one of said connection pads.

12-14 (canceled)

15.(original) A method of manufacturing an insulating sheet provided between a semiconductor chip and a wiring substrate comprising:

providing a metal film on one surface of said insulating sheet;

masking and etching said metal film to form a plurality of leads;

cutting out predetermined places of said insulating sheet to provide a plurality of holes through said insulating sheet; and

making one end of each of said plurality of leads fall into a corresponding one of said holes.

16.(original) A method of manufacturing an insulating sheet provided between a semiconductor chip and a wiring substrate comprising:

cutting out predetermined places of said insulating sheet to provide a plurality of holes through said insulating sheet;

fixing one end of each of a plurality of leads onto said insulating sheet; and

making the other end of each of said leads fall into a corresponding one of said plurality.